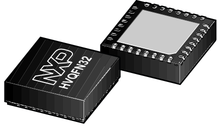

SOT617-19

HVQFN32, plastic, thermally enhanced very thin quad; flat non-leaded package; 32 terminals; 0.5 mm pitch; 5 mm x 5 mm x 0.85 mm body

4 October 2022 | Package information

1 Package summary

Terminal position code Q (quad)

Package type descriptive code HVQFN32

Package type industry code HVQFN32

Package style descriptive code HVQFN (thermal enhanced very thin quad flatpack; no leads)

Package body material type P (plastic)

Mounting method type S (surface mount)

Issue date 14-09-2022

Manufacturer package code 98ASA00656D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	5	-	mm
package width	-	5	-	mm
seated height	0.8	0.85	0.9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	32	-	

2 Package outline

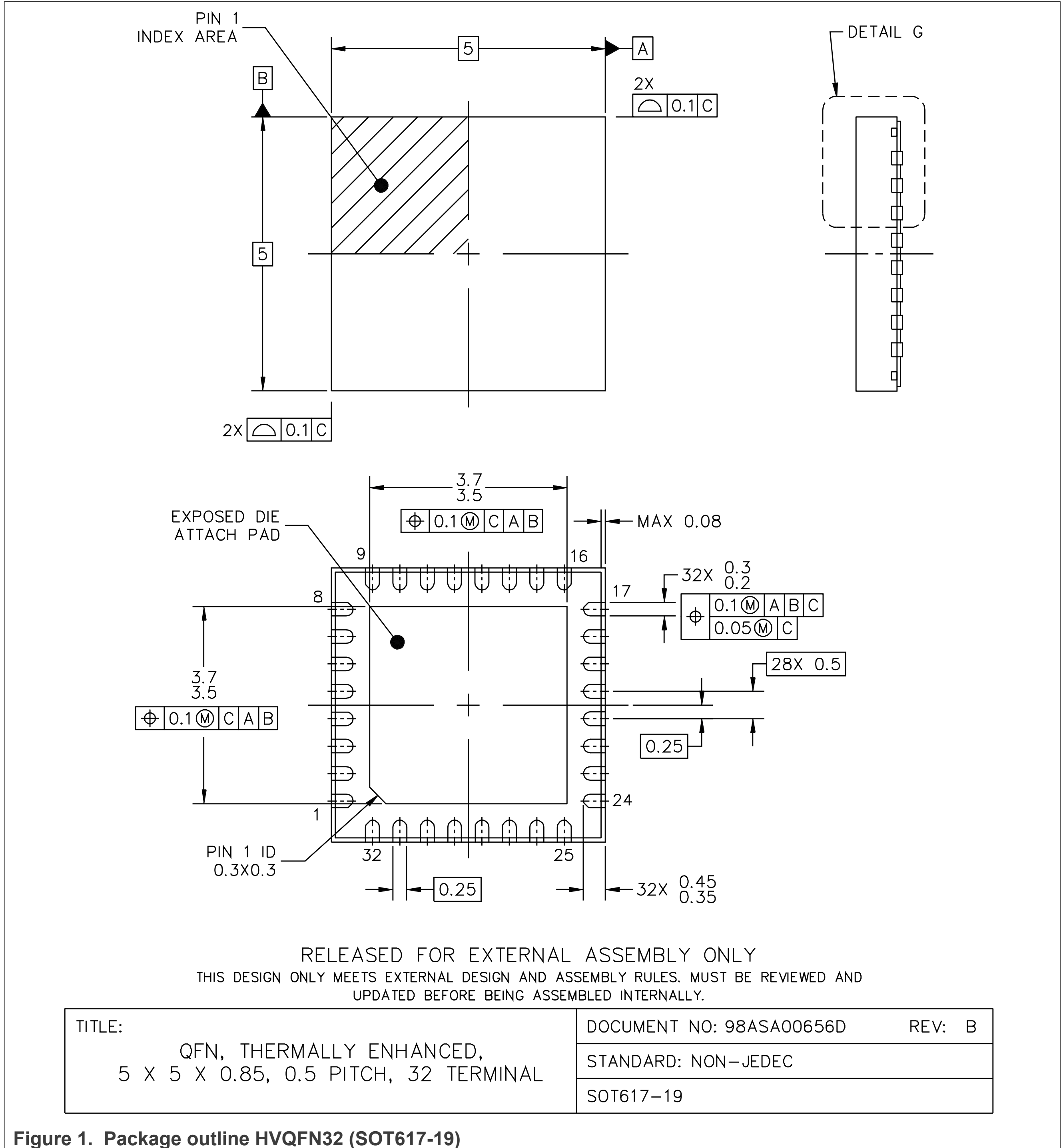

Figure 1. Package outline HVQFN32 (SOT617-19)

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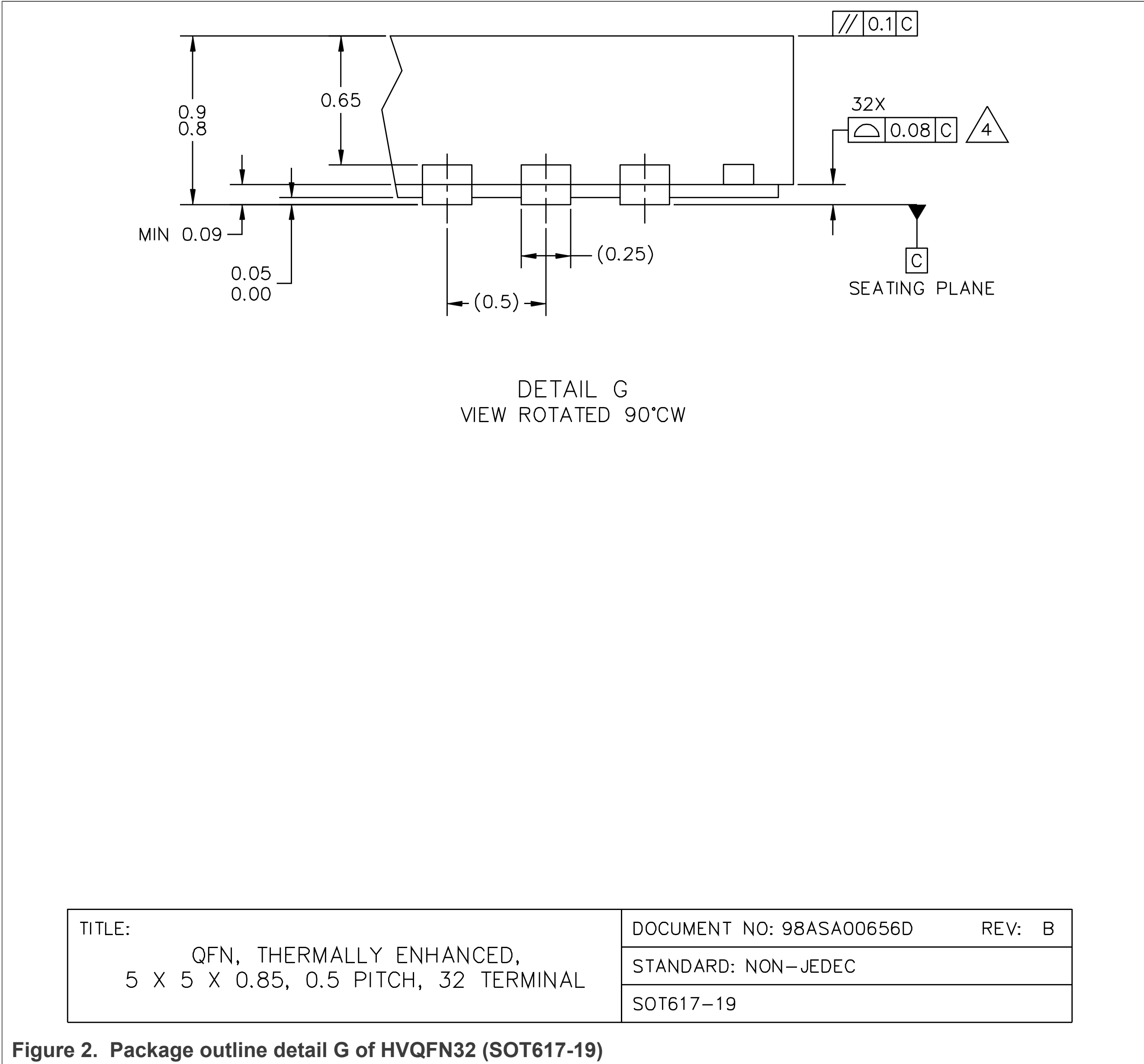

Figure 2. Package outline detail G of HVQFN32 (SOT617-19)

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3 Soldering

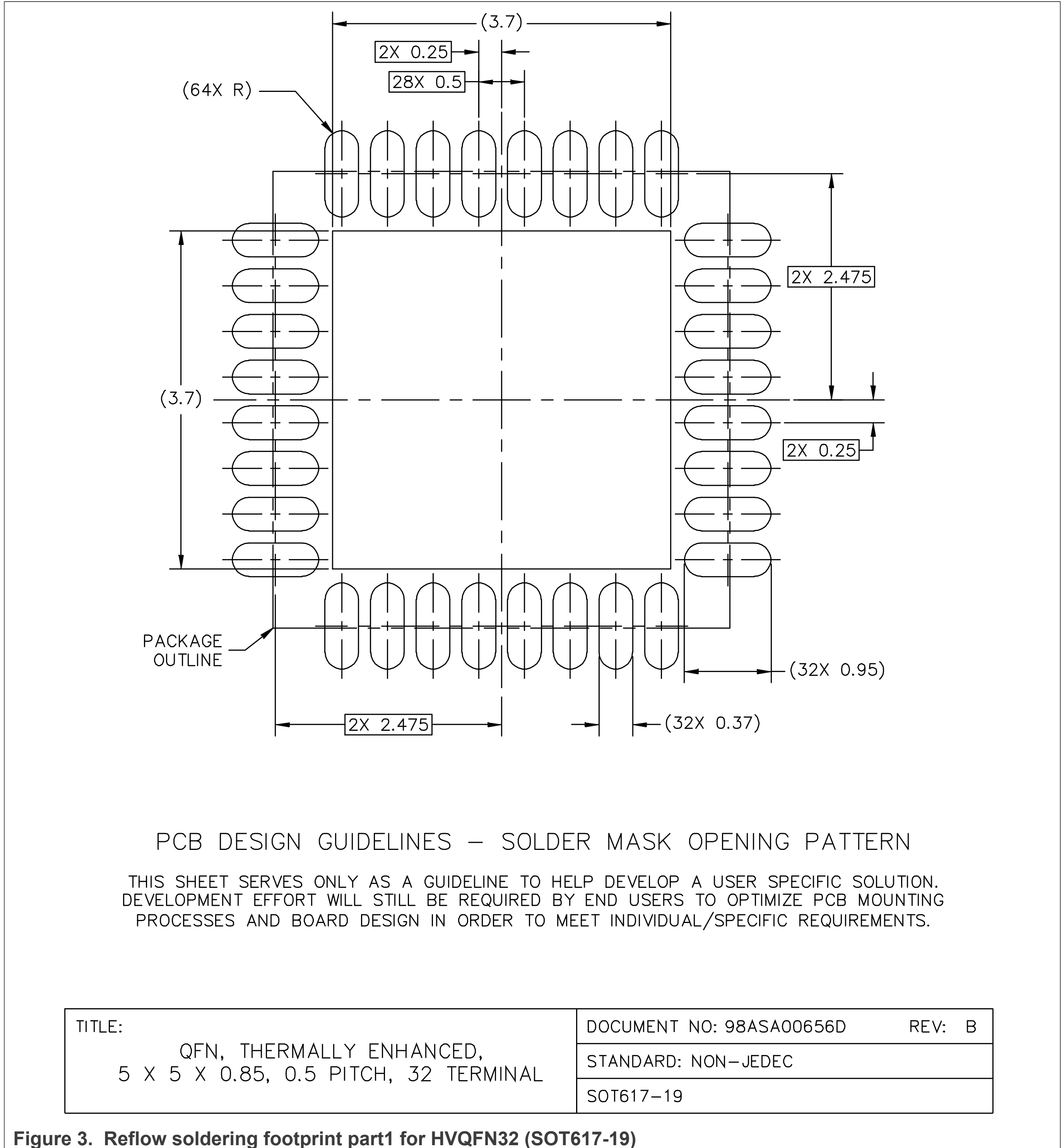

Figure 3. Reflow soldering footprint part1 for HVQFN32 (SOT617-19)

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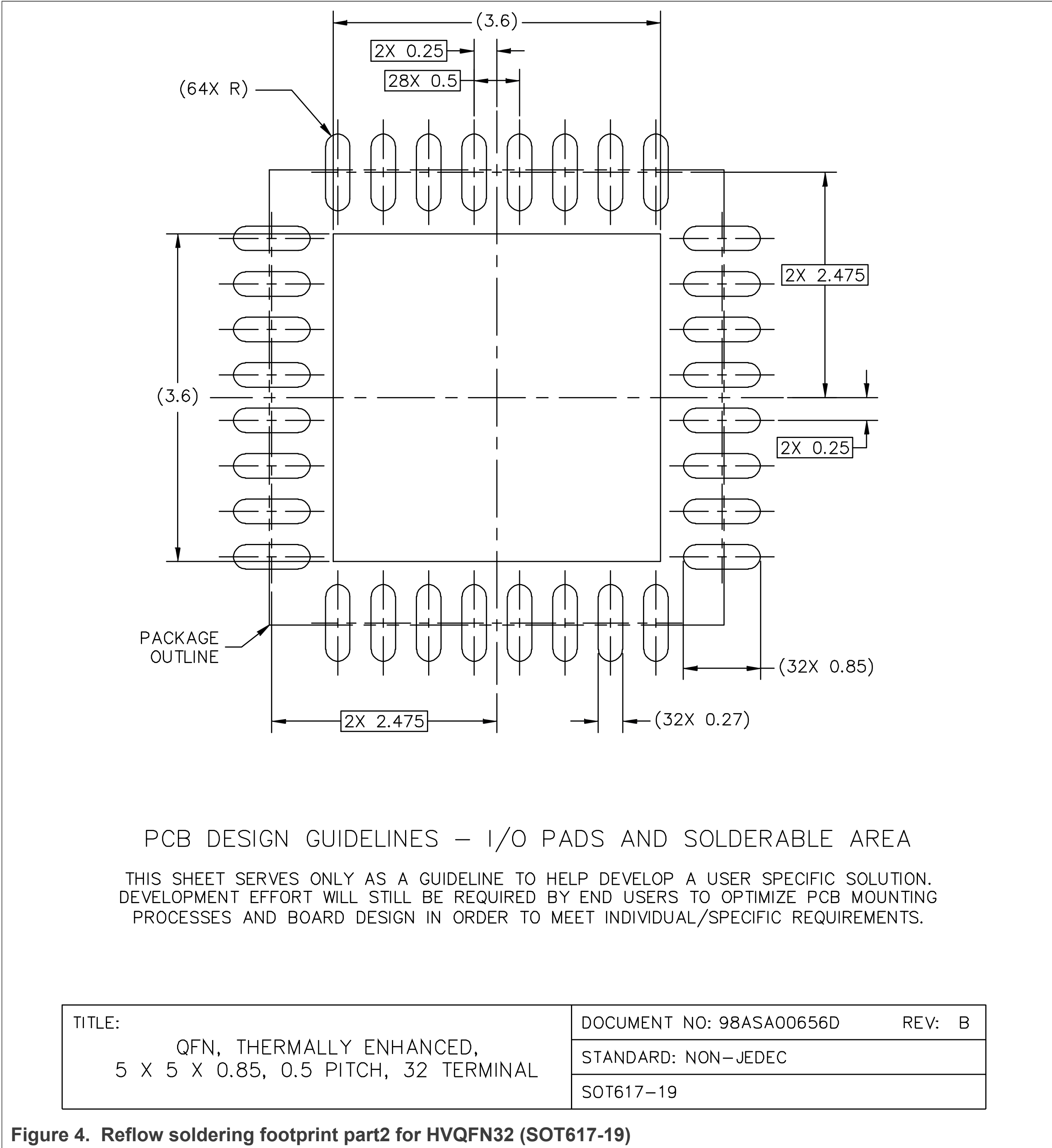

Figure 4. Reflow soldering footprint part2 for HVQFN32 (SOT617-19)

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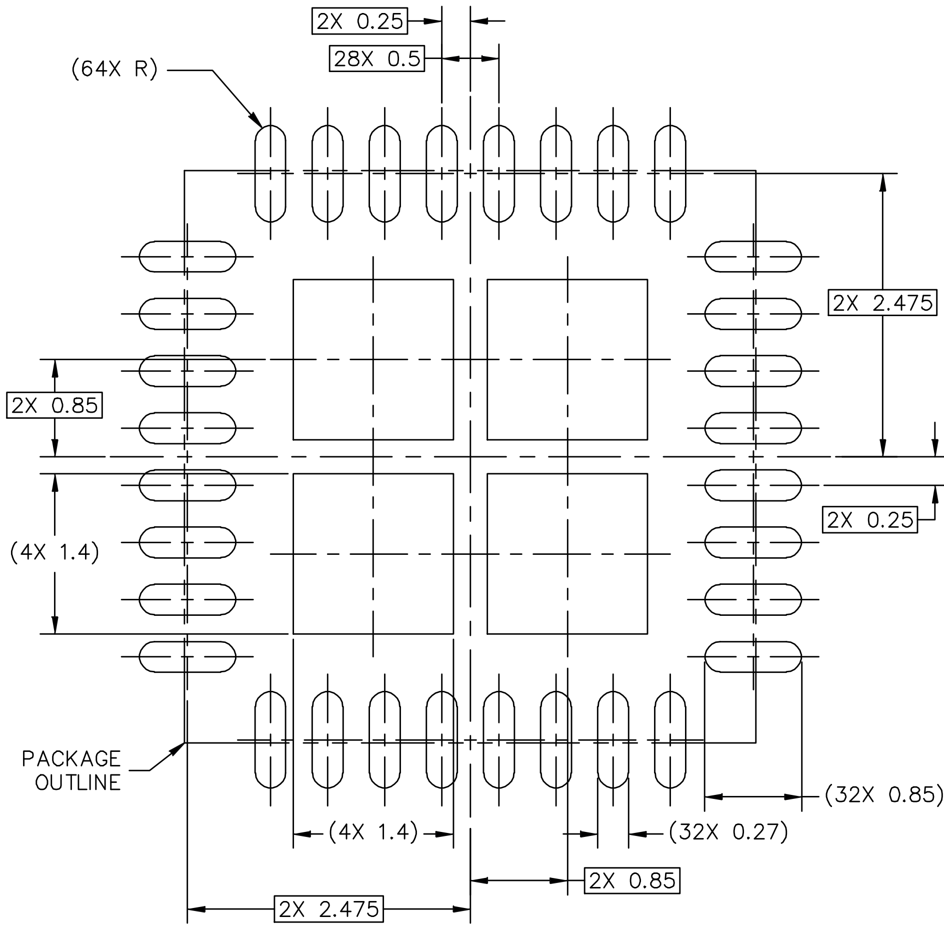

RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

TITLE: QFN, THERMALLY ENHANCED, 5 X 5 X 0.85, 0.5 PITCH, 32 TERMINAL	DOCUMENT NO: 98ASA00656D	REV: B
	STANDARD: NON–JEDEC	
	SOT617–19	

Figure 5. Reflow soldering footprint part3 for HVQFN32 (SOT617-19)

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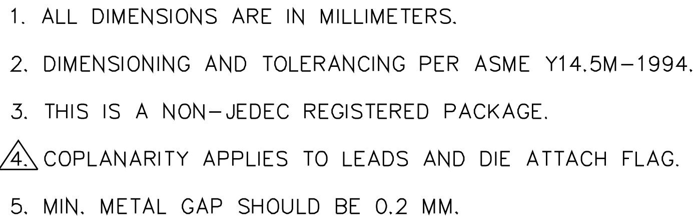
NOTES:



1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. THIS IS A NON–JEDEC REGISTERED PACKAGE.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

TITLE: QFN, THERMALLY ENHANCED, 5 X 5 X 0.85, 0.5 PITCH, 32 TERMINAL	DOCUMENT NO: 98ASA00656D REV: B
	STANDARD: NON–JEDEC
	SOT617–19

Figure 6. Package outline note HVQFN32 (SOT617-19)

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4 Legal information

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HVQFN32, plastic, thermally enhanced very thin quad; flat non-leaded package; 32 terminals; 0.5 mm pitch; 5 mm x 5 mm x 0.85 mm body

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